



A highly granular Silicon-Tungsten ECAL for the ILC

Vincent Boudry
École polytechnique, Palaiseau
for SiW-ECAL groups

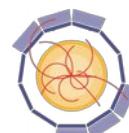


IT Accelerator Engineering Center ITAEC

**FJPPL 2017
IHPC, Strasburg
11/05/2017**



IN2P3
Les deux infinis



AIDA²⁰²⁰
TNA support + WP14



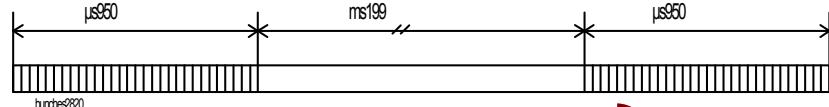
Involved persons & institutions

French Group			Japanese Group		
Name	Title	Lab/Organis.	Name	Title	Lab/Organis.
Vincent Boudry	Dr	LLR	Daniel Jeans	Assoc. Prof	KEK (formly. Tokyo)
Jean-Claude Brient	Dr	LLR	Taikan Suehara	Assist. Prof	Kyushu University
Vladislav Balagura	Dr.	LLR	Kiiyotomo Kawagoe	Assist. Prof	Kyushu University
Kostiantyn Shpak	PhD	LLR	Sachio Komamiya	Prof	Univ of Tokyo
Rémi Cornat	Dr.	LLR → LPNHE	Yoshio Kamiya	Prof	Univ of Tokyo
Roman Poeschl	Dr.	LAL	Izumi Sekiva	Master Student	Kyushu University
Dirk Zerwas	Dr.	LAL	Hiroaki Yamashiro	Master Student	Kyushu University
Adrian Irles	Dr.	LAL	Hitoshi nakanishi	Master Student	Univ. of Tokyo

2 “new” institutions

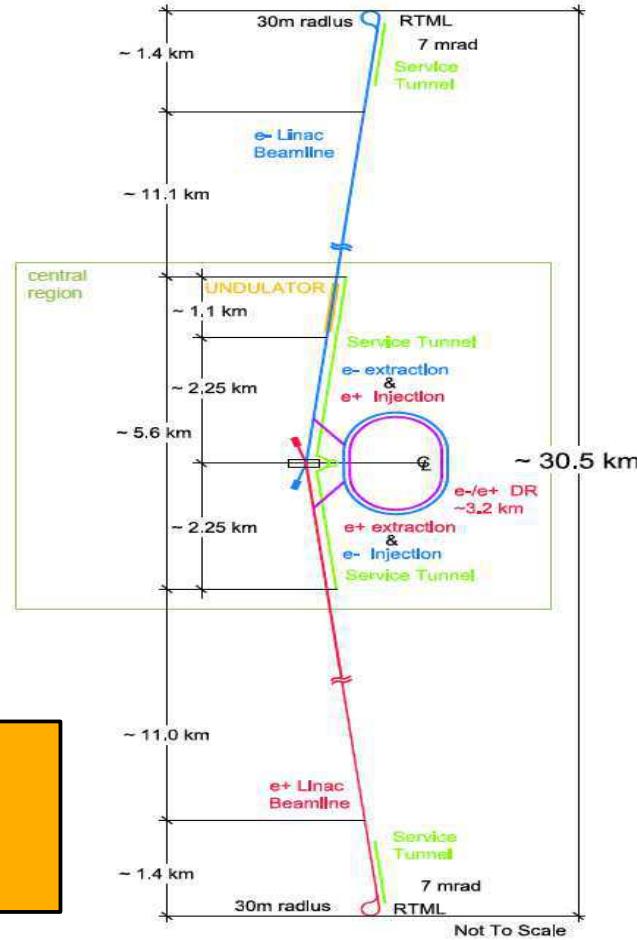
ILC parameters

Max. Center-of-mass energy	250–1000 (90)	GeV
Peak Luminosity	0.8–3x10 ³⁴	1/cm ² s
Beam Current	5.8	mA
Repetition rate	5	Hz
Average accelerating gradient	31.5	MV/m
Beam pulse length	0.95	ms
Total Site Length	31	km
Total AC Power Consumption	120–300	MW



- Time between collisions : 350–700 ns
- Trains of 1300–2700 Bunches
- Low detector occupancy
- Low bgd : $e^+e^- \rightarrow qq \sim 0.1 / BC$
 $\rightarrow \gamma\gamma \rightarrow X \sim 200 / BX$

- }
- High B field
 - Trigger-less
 - Power Pulsing ($\leq 1\%$)
 - Differed readout



Constraints on detectors:

Basis: sep of $H \rightarrow WW/ZZ \rightarrow 4j$

- $\sigma_z/M_Z \approx \sigma_w/M_W \approx 2.7\% \oplus 2.75\sigma_{sep}$

$\Rightarrow \sigma_E/E (\text{jets}) < 3.8\%$

- Sign $\sim S/\sqrt{B} \sim (\text{resol})^{-1/2}$
 $60\%/\sqrt{E} \rightarrow 30\%/\sqrt{E} \Leftrightarrow +\sim 40\% L$

Large TPC

- Precision and low X_0 budget
- Pattern recognition

High precision on Si trackers

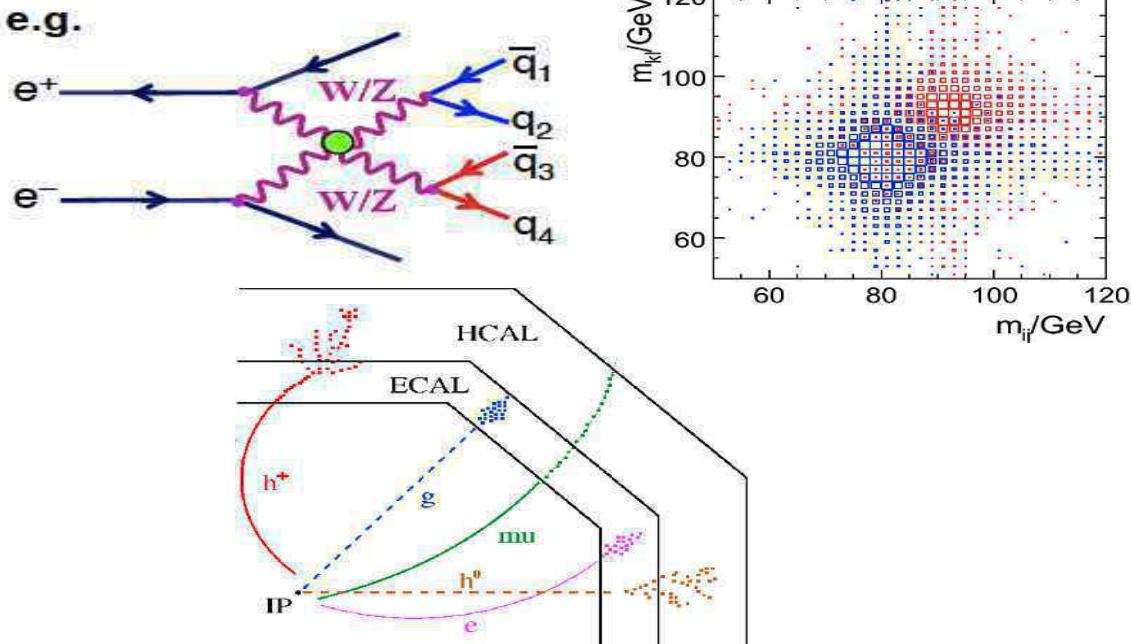
- Tagging of beauty and charm

Large acceptance

Fwd Calorimetry:

- lumi, veto, beam monitoring

Imaging Calorimetry



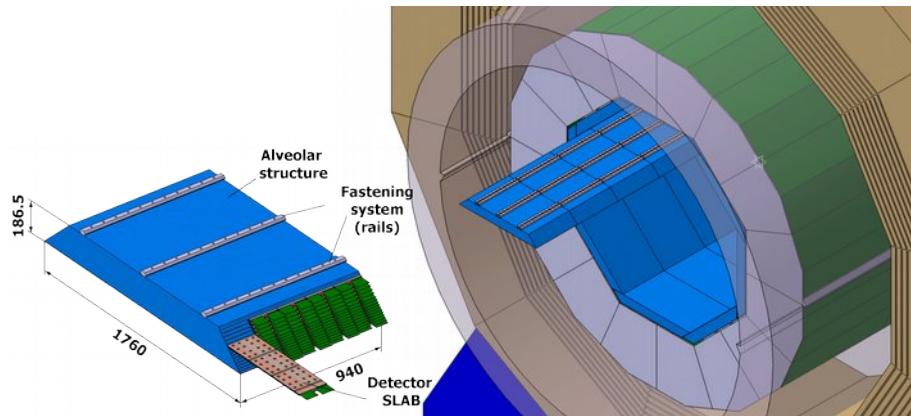
Particle Flow Algorithms :

- Jets = $65\% \text{ charged} + 25\% \gamma + 10\% h^0$
 Tracks ECAL CALO's

- $\text{TPC } \delta p/p \sim 5 \cdot 10^{-5}; \text{ VTX } \sigma_{x,y,z} \sim 10 \mu\text{m}$

H. Videau and J. C. Brient, "Calorimetry optimised for jets," in Proc. 10th International Conference on Calorimetry in High Energy Physics (CALOR 2002), Pasadena, California, March, 2002.

An Ultra-Granular SiW-ECAL for experiments



Particle Flow optimised calorimetry

- Standard requirements
 - Uniformity, Hermeticity, Stability, (E, x, t) Resolution
- PFlow requirements:
 - Extremely high granularity
 - Compacity (density)

SiW+C baseline choice for future Lepton Colliders

Basic Choices:

- Tungsten as absorber material

$X_0 = 3.5 \text{ mm}$, $R_M = 9 \text{ mm}$, $\lambda_l = 96 \text{ mm}$

Narrow showers

Assures compact design

- Silicon as active material

Support compact design

Allows for ~any pixelisation

Robust technology

Excellent signal/noise ratio: ≥ 10

Intrinsic stability (vs environment, aging)

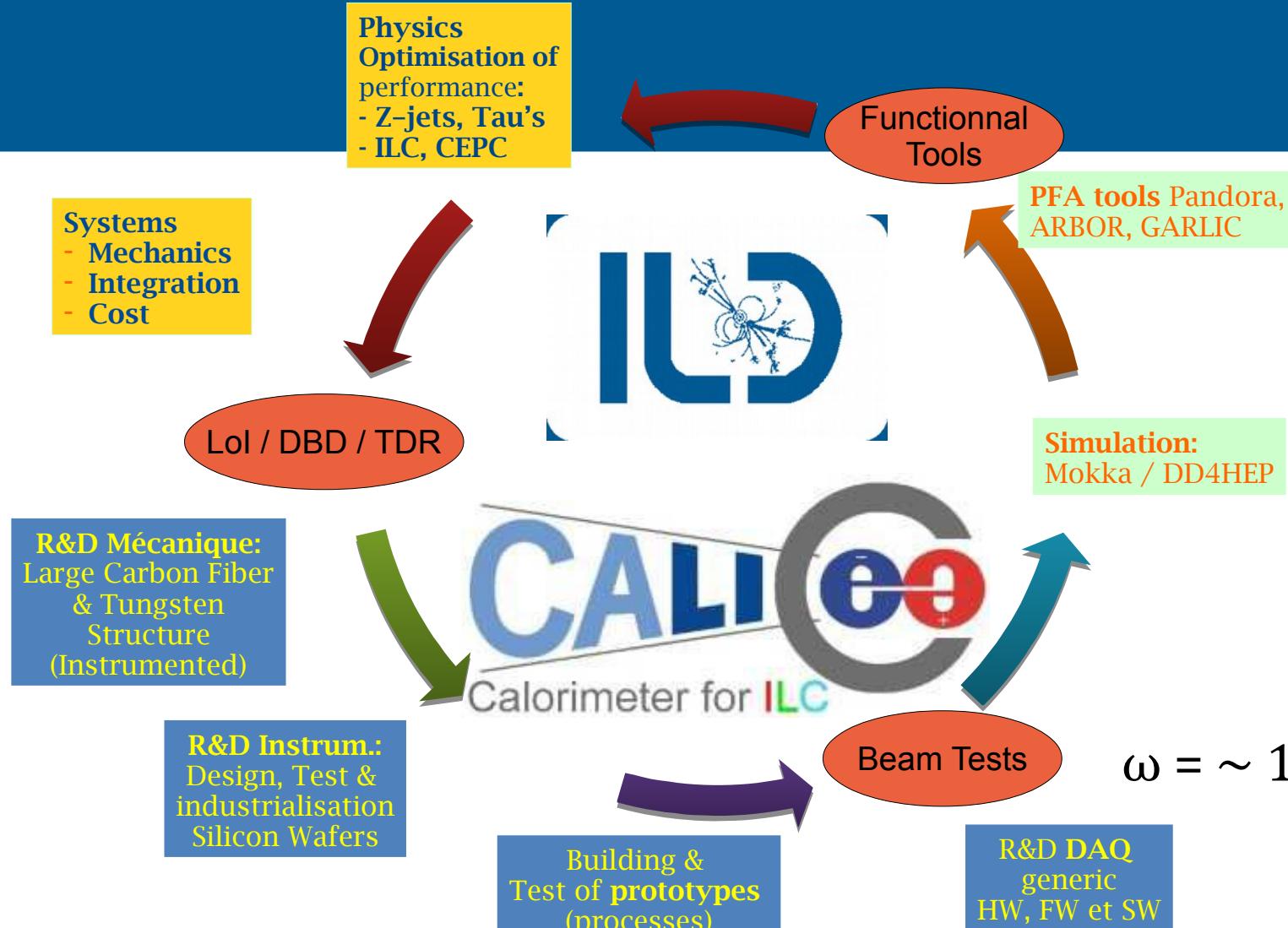
Albeit expensive...

- Tungsten-Carbon alveolar structure

Minimal structural dead-spaces

Scalability





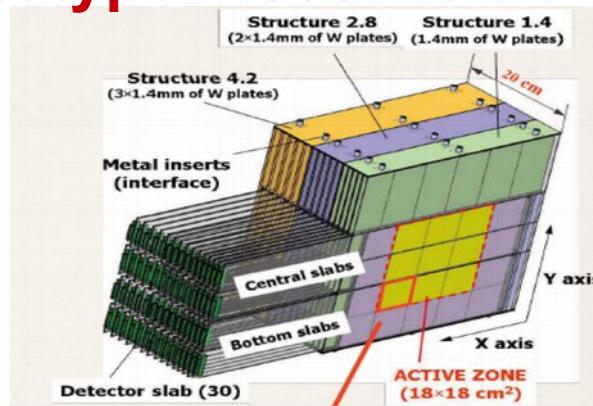
SiW ECAL: Physics & Technological prototype

Physics prototype: 2005–2011

PFA proof of concept
with comparison to MC
(PandoraPFA etc.)
Electronics outside

- 1cm x 1cm pixels
- full 30 layers

(used for PAMELA sat.)



**16.5% (stochastic) 1–2% (constant) obtained
with 1–45 GeV e⁻/e⁺ at 2006/2008 BT**

Assess the feasibility:

Establish procedures and develop
test benches for mass production : **AIDA-2020, pre-prod test benches.**

- 10 000 SLAB's \supset ~75 000 ASU to be produced for ILD

Technological prototype



Embedded electronics

- SKIROC2 analog/digital ASICs
 - auto-triggered, zero suppr., PP
- pixels 5x5mm²

ILD Building blocks: SLAB's & ASU's

R&D for “mass production” and QA

- Quality tests & preparation of large production
- Modularity → ASU & SLABs
- Choice of square wafers
 - (\neq from hex: SiD, CMS HGCAL)

Numbers ($R_{ECAL} = 1.8$ m, $|Z_{Endcaps}|=2.35$ m)
(likely to be reduced by 30–40%)

- Barrel modules: 40 (as of today all identical)
- Endcap Modules: 24 (3 types)
- ASUs = ~75,000
 - Wafers ~ 300,000 (2500 m²)
 - VFE chips ~ 1,200,000
 - Channels: 77Mch
- Slabs = 6000 (B) + 3600 (EC) = 9600
 - \neq lengths and endings

Tests of producibility

Tests of feasibility

PCB (FeV)
16 SK2 ASICs
1024 channels

ASU

Wafer (4)

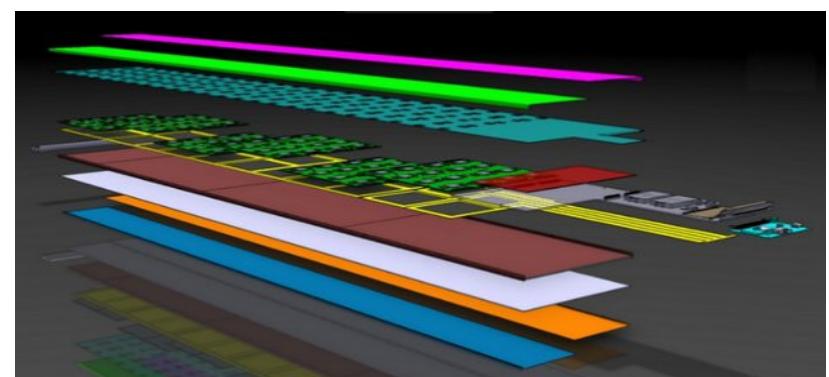
Copper (cooling)

Shielding

Adapter board (SMB)

Carbon+W

U layout of a short slab

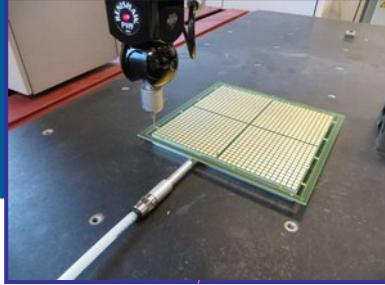


U layout of a long slab

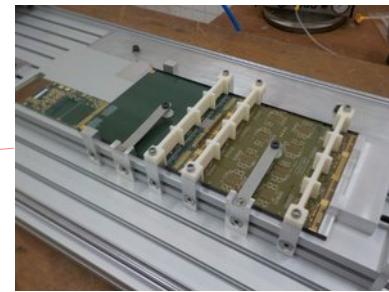
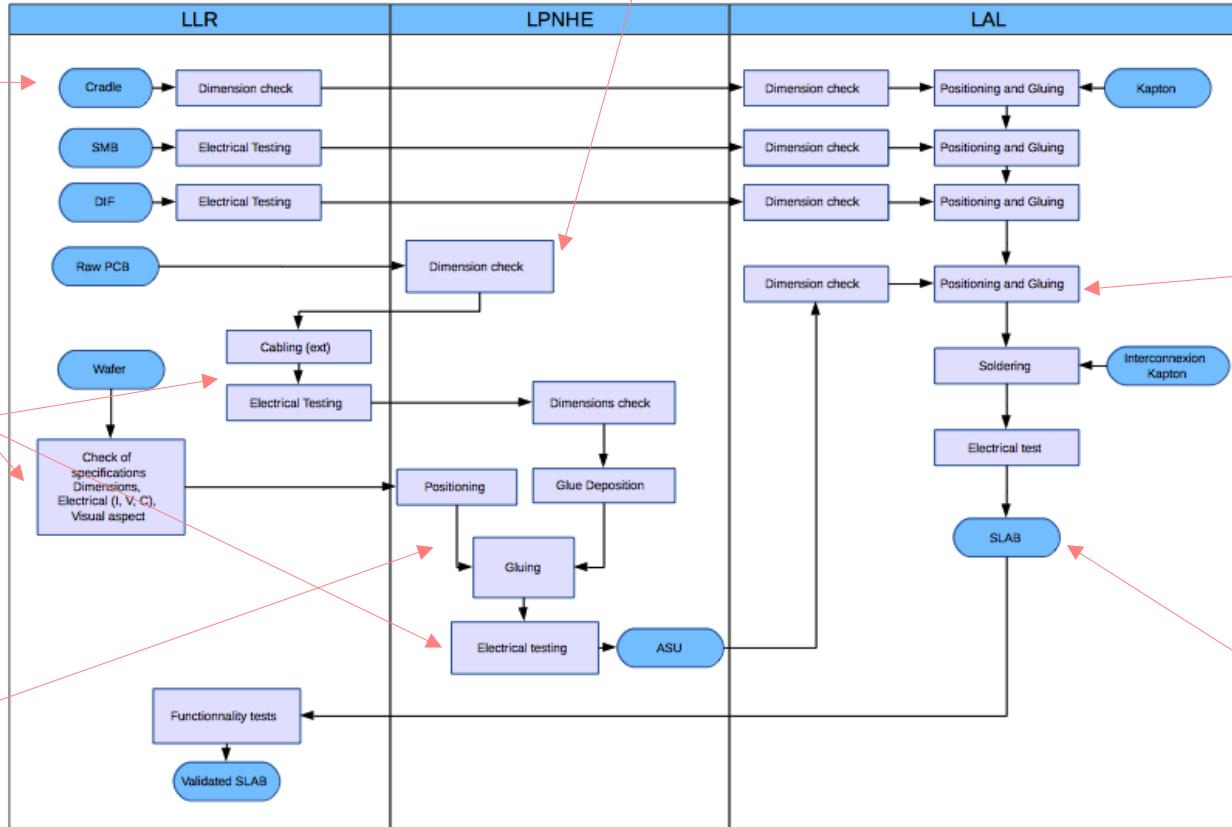
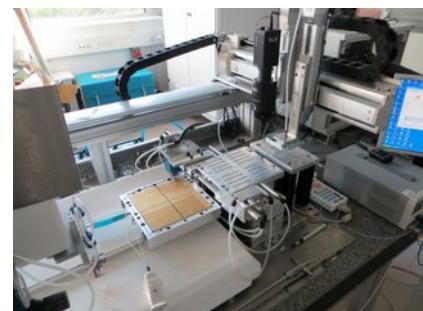
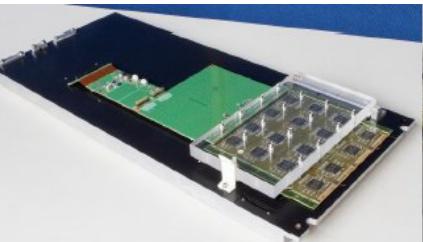
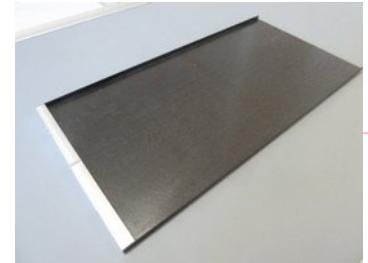
Full assembly chain

resp: R. Cornat

LLR, LPNHE, LAL



'Simplified view'



Beam test 2017: Prototype

with 10 first^t SLAB's

- noise handling
 - Scans.
 - Time dependance ?
 - PS dependance ?
- Cosmic data taking
 - \triangle hasher running conditions...
(longer integration time)

Beam test in 12–24 June @ DESY

- Readiness review mi-April

Analysis + of nov 15 data.

- \Rightarrow Start of assembly for second batch ...

DESY Testbeam Schedule 2017 - Version 9- 28/02/2017
Ralf Dienert, Norbert Meynars, Marcel Stanitzki - DESY Test Beam Coordinators

Week	TB21	TB22	TB24/1	TB24
2-Jan-17	1			
9-Jan-17	2			
16-Jan-17	3			
23-Jan-17	4			
30-Jan-17	5			
6-Feb-17	6			
13-Feb-17	7			
20-Feb-17	8			
27-Feb-17	9			
4-Mar-17	10			
11-Mar-17	11			
18-Mar-17	12			
25-Mar-17	13			
1-Apr-17	14			
8-Apr-17	15			
15-Apr-17	16			
22-Apr-17	17			
29-Apr-17	18			
6-May-17	19			
13-May-17	20			
20-May-17	21			
27-May-17	22			
3-Jun-17	23			
10-Jun-17	24			
17-Jun-17	25			
24-Jun-17	26			
1-Jul-17	27			
8-Jul-17	28			
15-Jul-17	29			
22-Jul-17	30			
29-Jul-17	31			

Shutdown

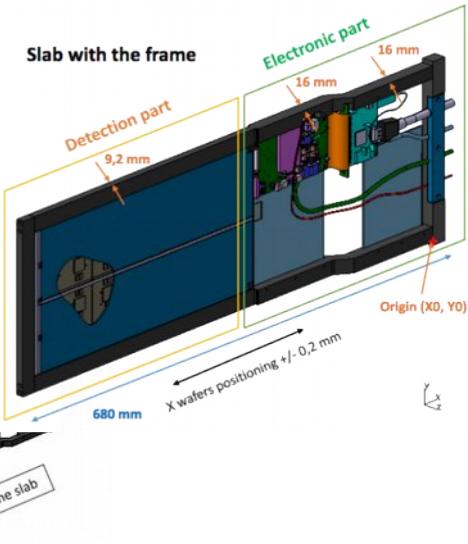
Startup

BELLE-II

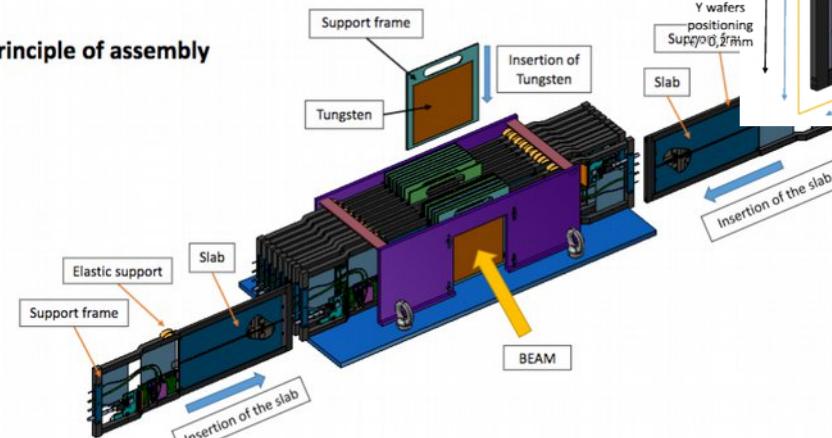
Summer Shutdown

\Rightarrow Test of 15–20 SLABs early in 2018

- with new structure [Guillaume]

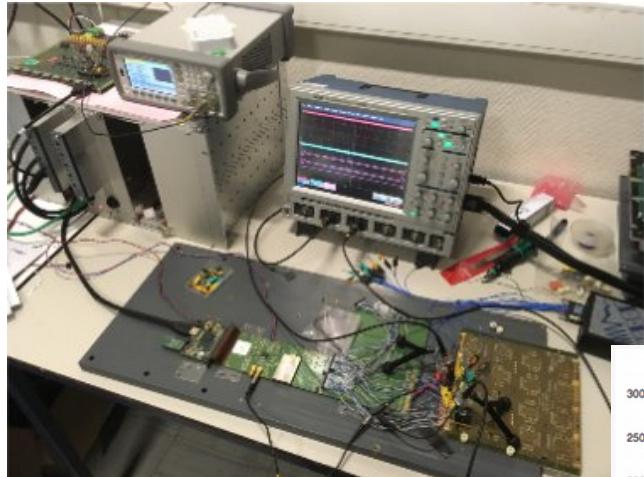


Principle of assembly

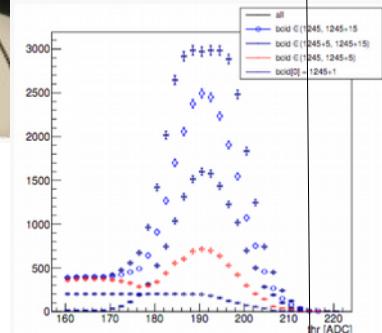


VFE ASIC [LLR, Kyushu]

Omega Skiroc2 vs Skiroc2a



Same with
SK2CMS

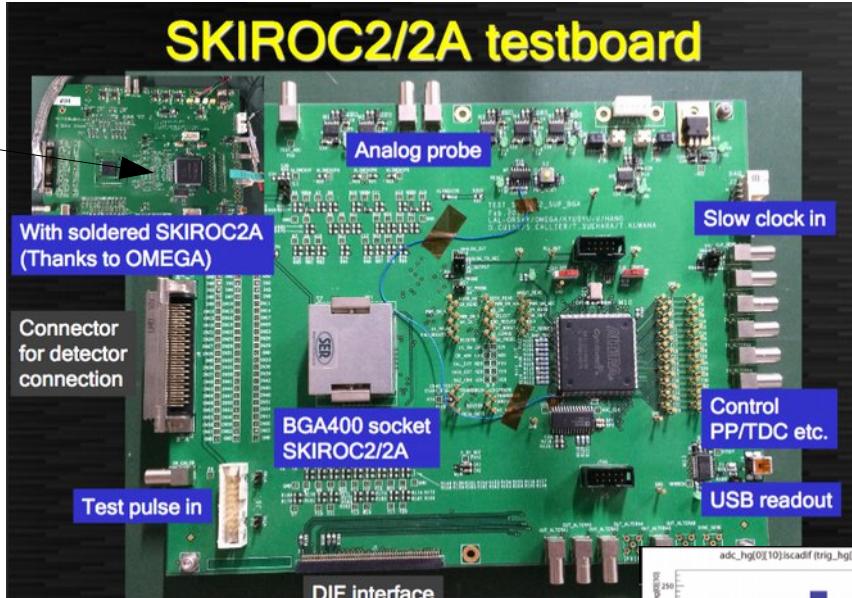


Socket test of ASICs on ASU

- Noise & functional checks
 - trigger (over)efficiency, tagging, ADC, TDC, ...
- Running modes for Beam Tests
 - ↔ Full SLABS

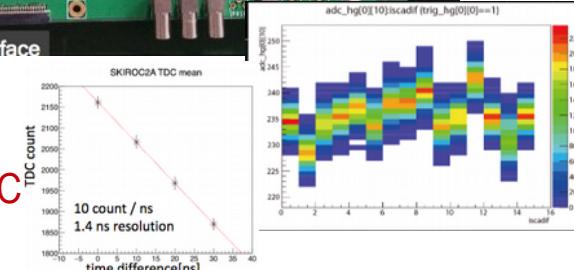
Vincent.Boudry@in2p3.fr

V. Boudry, S. Chaitanya, A. Lobanov (LLR)
ILD SiW ECAL | FJPPL, IPHC | 11/05/2017



Dedicated Test board

- for optimal use of ASIC (all protections)
- Systematic test of protections (on-going)



I. Sekiya, T. Suehara (Kyushu University)

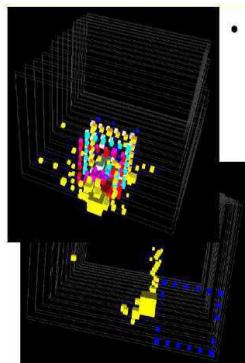
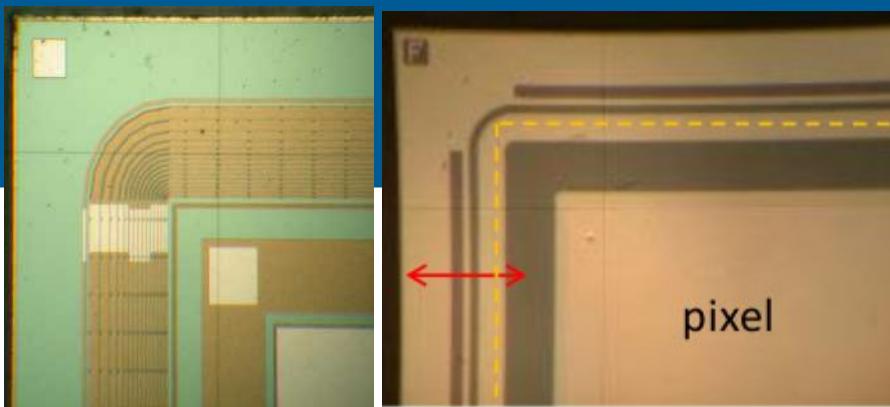
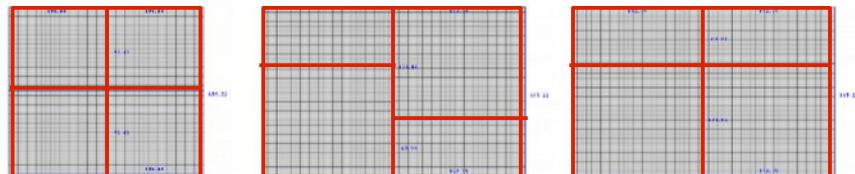
Silicon Sensors

Cost driven

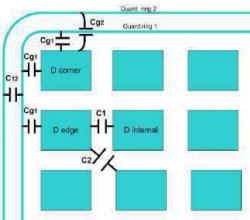
- ~30% of the total cost of the SiW-ECAL
 - ⇒ Units Cost reduction(CALIIMAX program)
- Decoupling of Guard Ring (Square Events).
- new design of ILD detector

Command Sensors @ Hamamatsu

- ⚠ Minimal cost of Command $\geq 20k\text{\euro}$
- direct contact with HPK engineers
 - (last @ LCWS'2016)
- Possibility of design for 8" in 186mm alveola
-



- "Square events"
 - cross talk between guard rings and pixels



'quantum unit' of ILD
dimensions (here 4" wafer)

Wafers [LLR, Kyushu]

“Edgeless wafers” integrated in 2 of the 10 SLABs (2016)

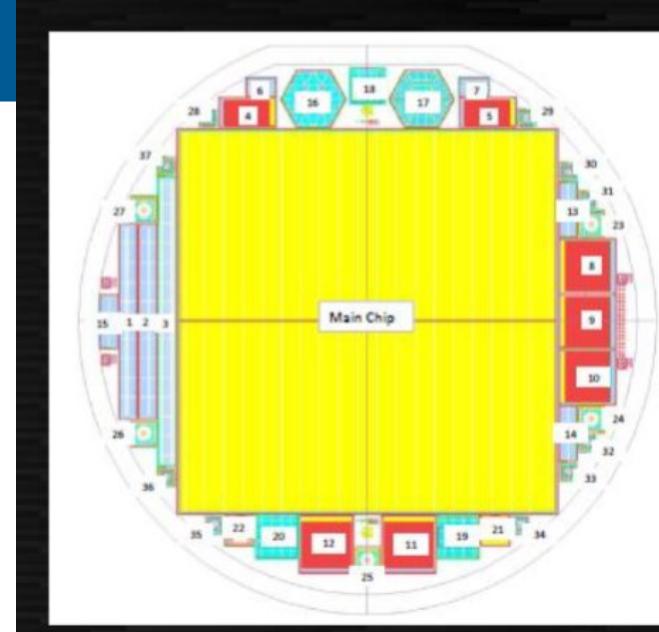
- needs BT data (with muon beam → edge scan)
 - Beam Tests June 2017 @ DESY

Baby sensors

- HPK change or resistivity in 2013
- Parasitic production

Position Sensitive Detector

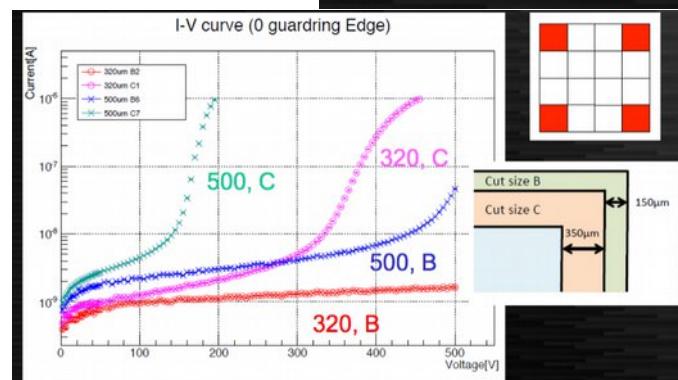
- Laser scan
 - reconstruction.



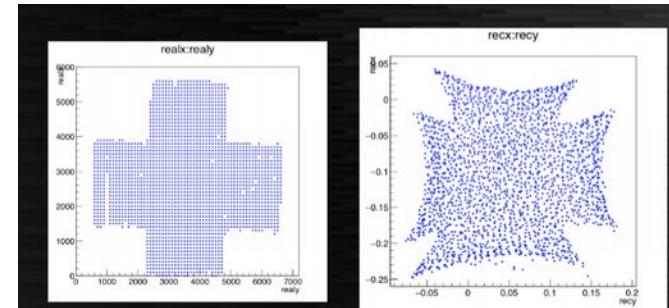
320 μm thickness
lower resistivity

16,17: Hexagon
(hexagonal cells,
triangular cells)
19,20: 4x4 (small pix)
(0 GR, 2 GR, 2.5 mm)
21,22: PSD (7 mm)
(meshed, non-meshed)

Each > 40 sensors

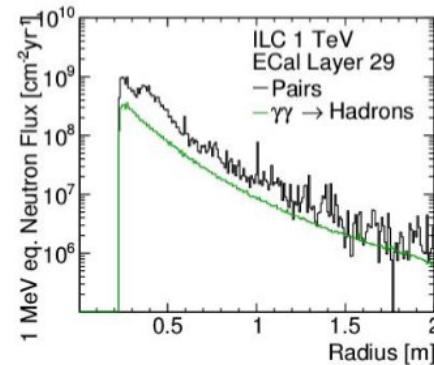
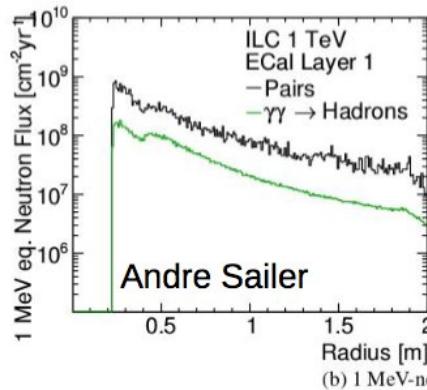


Prelim PSD reconstruction



Irradiation tests [Tokyo]

Expected dose in ECAL endcaps (1 TeV ILC)



Expected dose in ECAL endcaps (1 TeV ILC) [ext^{ed} from CLIC studies]

- inner part of ECAL endcap: up to 10^9 1MeV eq. neutrons / cm^2 / year

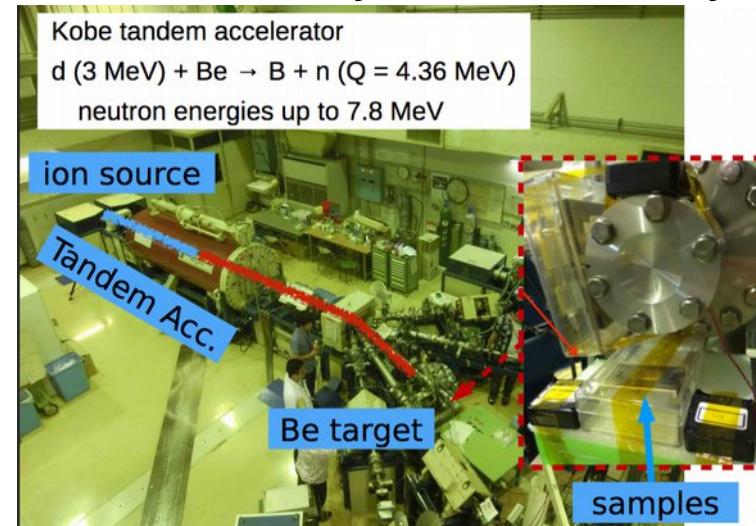
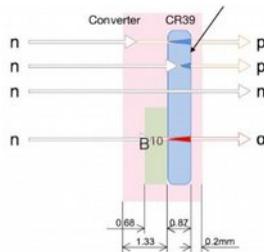
Test of

- super-capacitor (AVX BestCap, 400mF)
- conductive glue: EPOTEK
- sensor HPK baby ECAL sensor (3x3 pixels) [standard guard ring design]

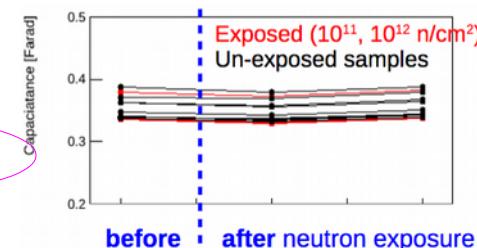


H. Nakanishi, C. Kozakai, Y. Kamiya, D. Jeans, S. Komamiya

Flux meas.
using CR30



- Capacitance ✓
- Resistance ?
- OK but puzzling
- I to V curve ✓
- lim. to ASIC
- for 50 years of ILC



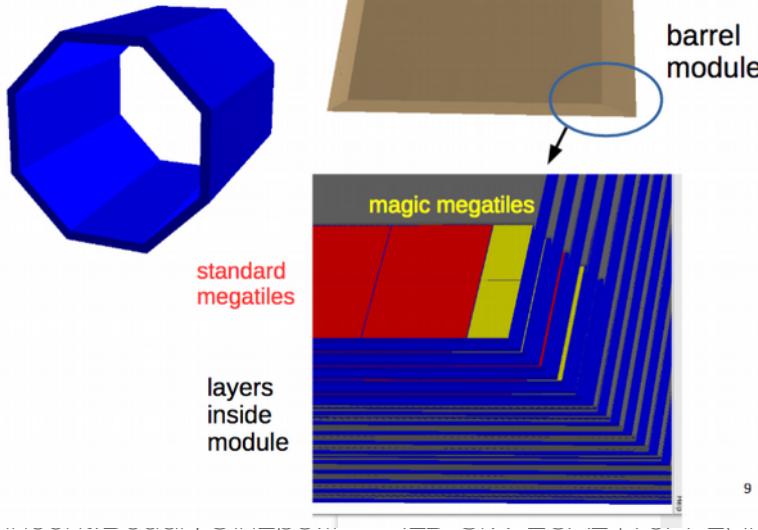
No sign of
damage

New Simulation [D. Jeans]

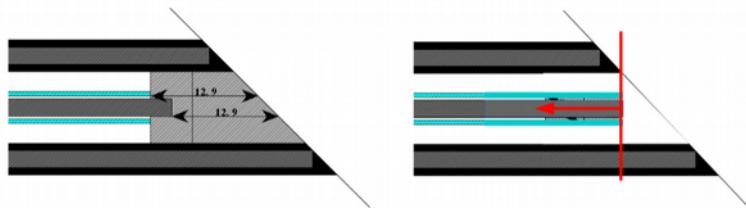
ECAL driver used in ILD models has been largely re-written (Mokka → DD4HEP)

- more modular code:
- less duplication Barrel & Endcap
- more configurable...

ECAL barrel



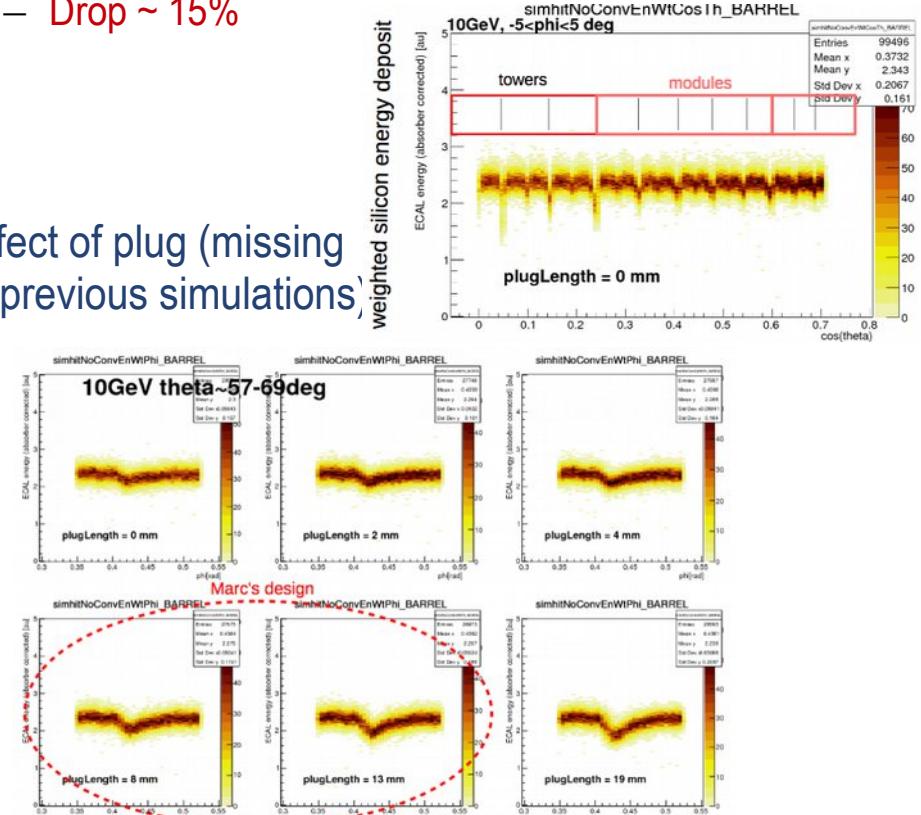
9



Effect of cracks [RAW= no correction at all!!]

– Drop ~ 15%

Effect of plug (missing in previous simulations)



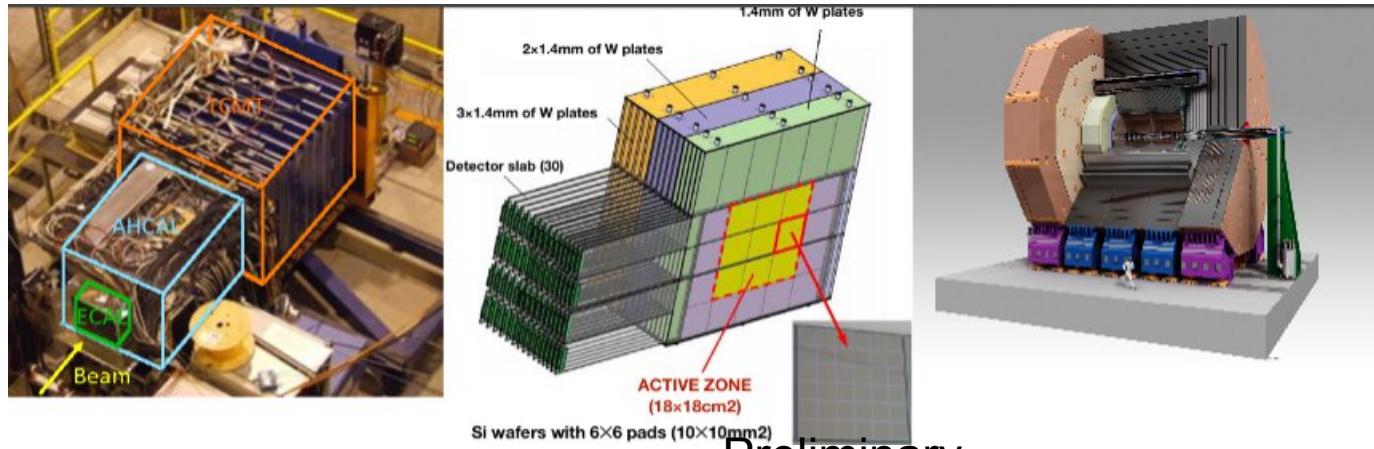
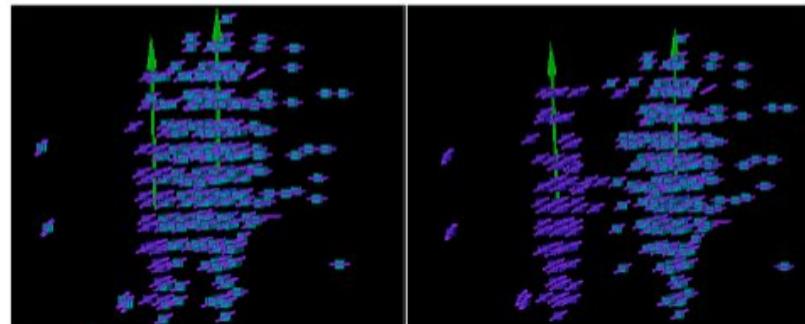
Performances: photon reconstruction confusion studies [K. Shpak]

“raw performances”

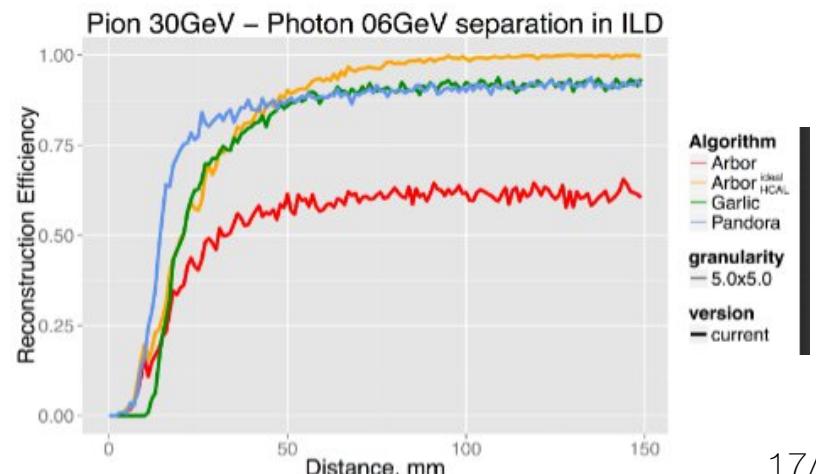
- Efficiency vs separation distance
- EM vs EM (e / γ)
- EM vs π

Using Particle Flow Algorithms

- PandoraPFA, Arbor (IHEP/LLR)
- GARLIC (LLR, Tokyo)



Preliminary



Performances: tau reconstruction [D. Jeans]

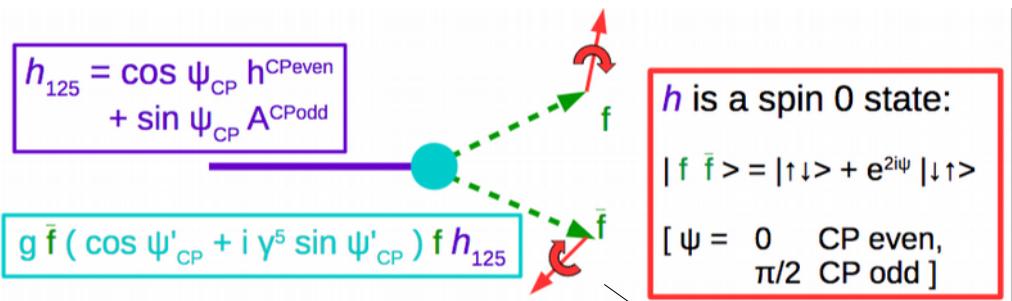
CP State analysis in $H \rightarrow \tau\tau$

T. Hieu et al, "Tau decay identification in ILD" arXiv:1510.05224

Using GARLIC

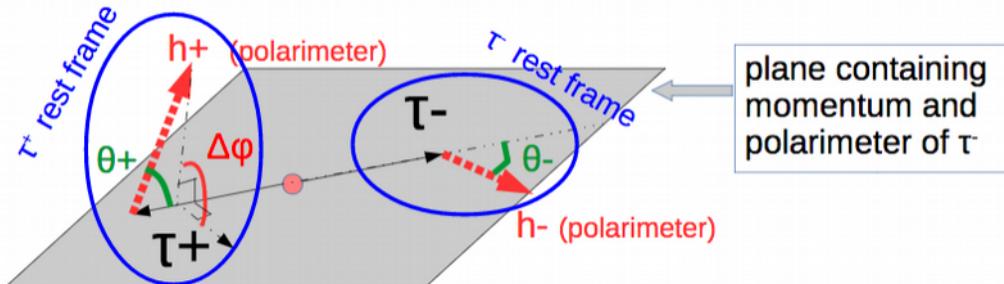
Higgs CP state and CP conservation in coupling

CP of $H \rightarrow ff$ through polarisation of f



Through decay

CP from polarimeters : taus from spin 0 parent



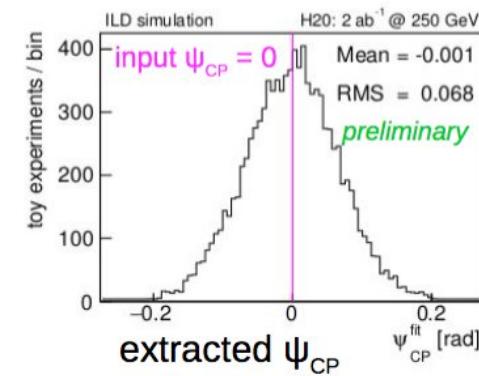
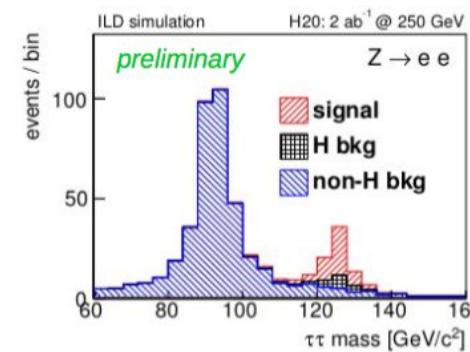
Best for τ in $ee \rightarrow ZH$, $Z \rightarrow ee$, $qq \rightarrow \tau\tau$

$H \rightarrow \tau\tau$

– Needs full τ reconstruction

- in hadronic tau decays (# neutrino = 1), if we know the tau **production vertex**, the **impact parameters** of charged tau decay products, the p_T of the tau-tau system,

then the neutrino momenta can be reconstructed



Prospects

Very active collaboration between

- LLR, LAL, (LPNHE)₂₀₁₇ + *Omega*
- Tokyo, Kyushu + KEK₂₀₁₇

Pure R&D (CALICE):

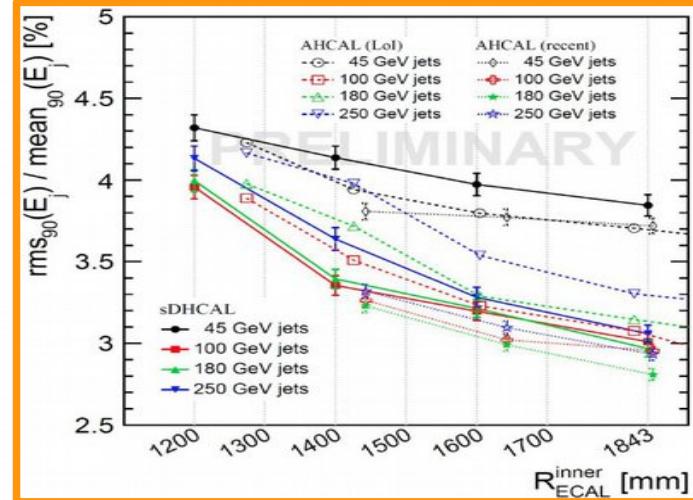
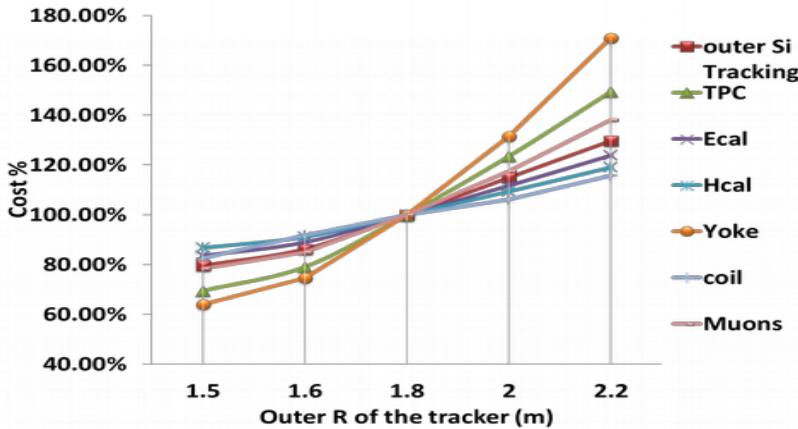
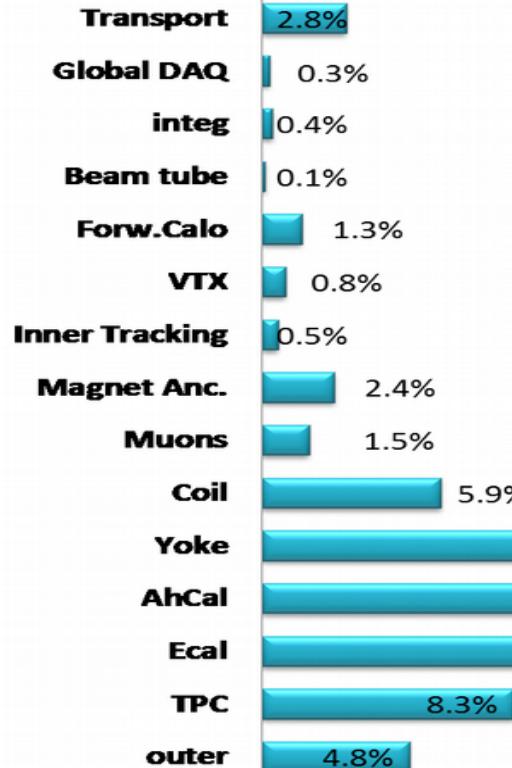
- test of ASIC (test benches, material, experience)
- test of wafers (contact with Hamamatsu)
- beam test and irradiation tests

Toward ILD detector re-design

- Consolidated baseline & small radius
- Simulation
- Mechanical design
- Performance studies
- Physics & Detector analysis

Extras

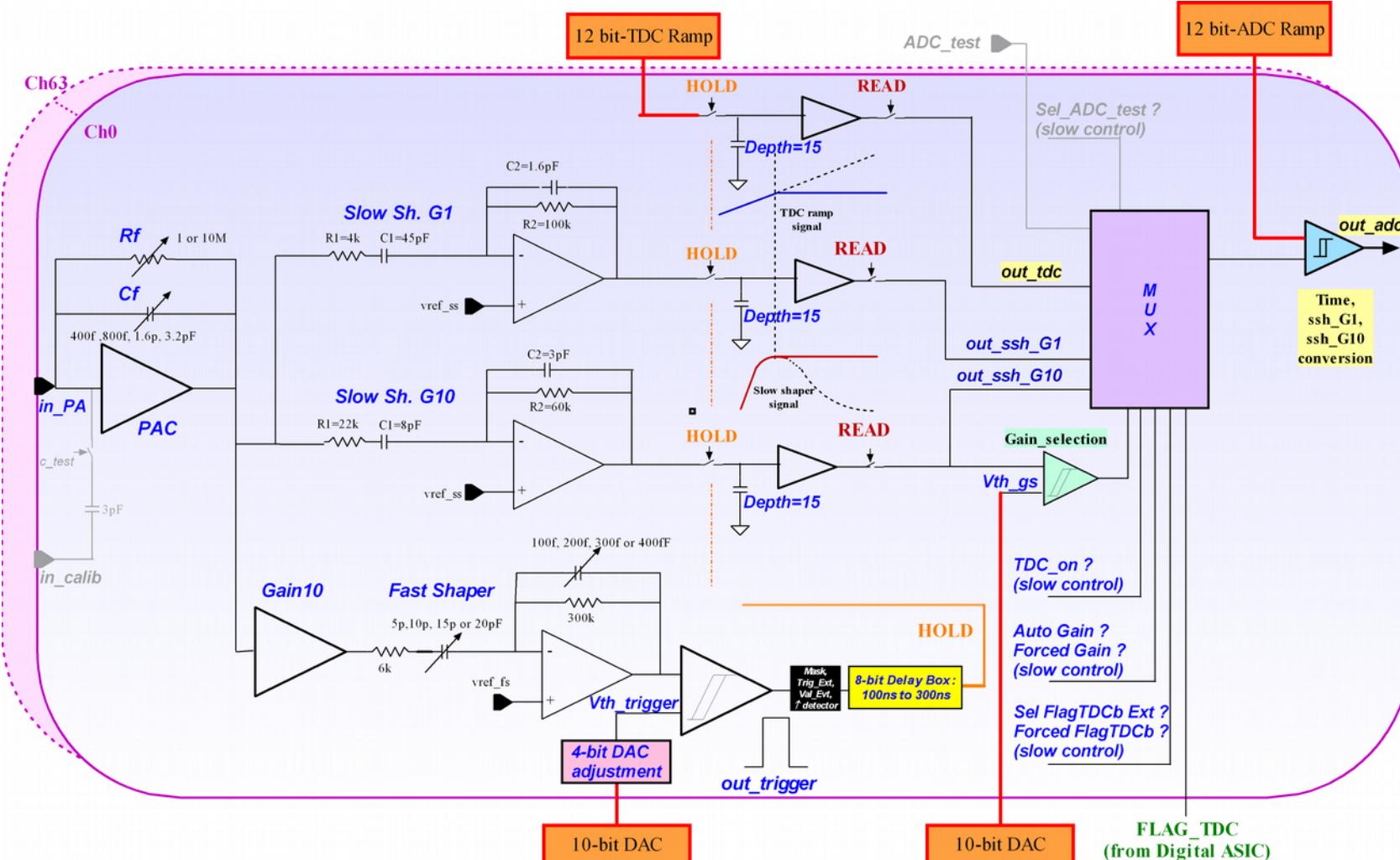
Structure de coût d'ILD



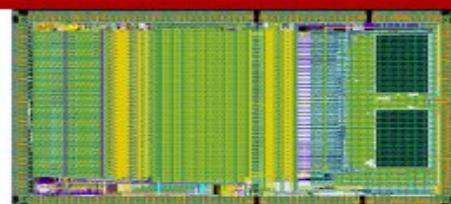
Full Silicon
option

SKIROC2 / 2A Analogue core

Ωmega



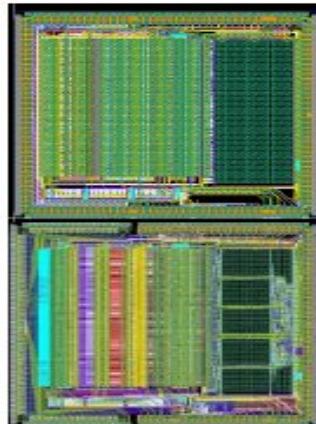
ROC chips for ILC prototypes



SPIROC2

Analog HCAL (AHCAL)
(SiPM)
36 ch. 32mm²

June 07, June 08, March 10, Sept 11



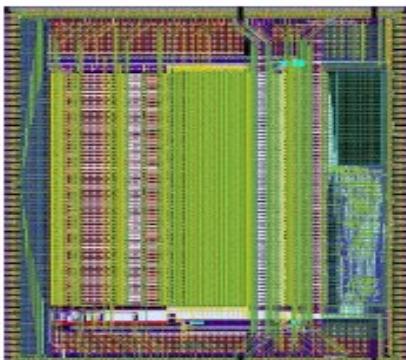
HARDROC2 and MICROROC

Semi Digital HCAL (sDHCAL)
(RPC, umegas or GEMs)
64 ch. 16mm²

Sept 06, June 08, March 10



AIDA



Agence Nationale de la Recherche
ANR

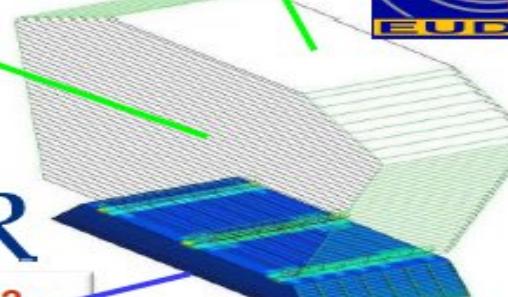
SKIROC2

ECAL

(Si PIN diode)
64 ch. 70mm²

March 10

<http://omega.in2p3.fr>

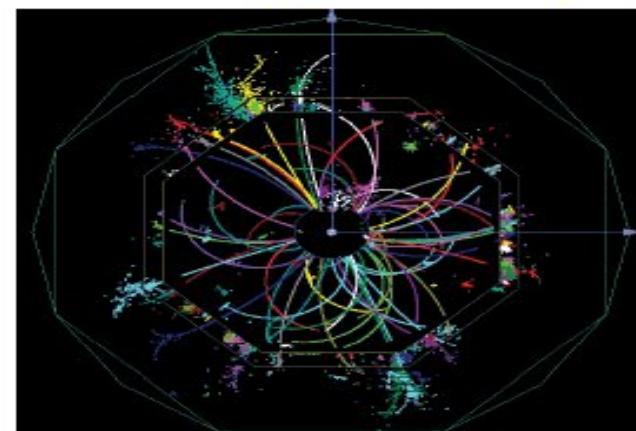


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ROC chips for **technological prototypes**: to study the feasibility of large scale, industrializable modules (Eudet/Aida funded)

Requirements for electronics

- Large dynamic range (15 bits)
- Auto-trigger on ½ MIP
- On chip zero suppress
- **10⁸ channels**
- Front-end embedded in detector
- **Ultra-low power : 25µW/ch**



SKIROC2A

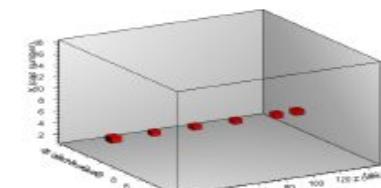
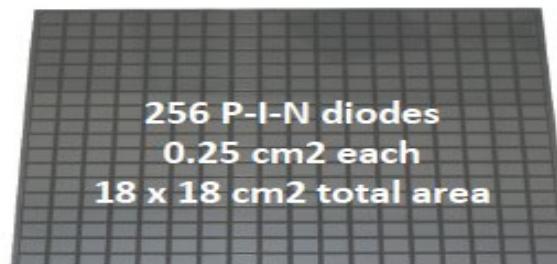
by S. Callier, C. de la Taille

- **BUG CORRECTIONS**

- Some « Zero events » during digitization : **DONE** (added delays, cf. SP2C)
- Substrate Shielding, Inputs Shielding : **IMPROVED** (added connections)
- Test mode for naked dies (voltage drop off & missing pads) : **CORRECTED**
- Trig Ext path no more thru delay cells to store the analog data : **DONE**

- **IMPROVEMENTS**

- 4-bit DAC for trigger level adjustment : **OPTIMIZED**
- Bandgap : **CHANGED** (from HR3)
- Delay Cell : **Slightly IMPROVED**
- AutoGain Selection : **CHANGED** (from SP2C)



Production possible
through CMS-HGCAL
collaboration

Prototyping : who is doing what

© R. Cornat

The collage consists of nine panels arranged in a grid:

- Carbon – W composite**: A photograph of a stack of carbon and tungsten composite material.
- LUR**: Handwritten red text "LUR" appearing in three different locations.
- ASIC (SKIROC)**: A photograph of an Application Specific Integrated Circuit (ASIC) die labeled "SKIROC".
- OMEGA**: A photograph of an OMEGA detector module.
- Simulation Analysis**: A photograph of simulation analysis software showing a plot of signal versus energy.
- Cooling system**: A photograph of a complex cooling system with many wires and heat sinks.
- LUR**: Handwritten red text "LUR" appearing in two different locations.
- PIN diodes**: A photograph of PIN diodes on a substrate.
- KYUSHU UNIVERSITY**: The logo of Kyushu University.
- LUR**: Handwritten red text "LUR" appearing in one location.
- LPSC Grenoble**: The logo of LPSC Grenoble, with the text "Laboratoire de Physique Subatomique et de Cosmologie".
- Sensor Gluing**: A photograph of a sensor being glued onto a substrate.
- LPNHE Paris**: The logo of LPNHE Paris.
- Power pulsing**: A photograph of a power pulsing circuit board.
- LUR**: Handwritten red text "LUR" appearing in one location.
- DAQ**: The acronym DAQ (Data Acquisition) in blue.
- Front-end board**: A photograph of a front-end board with various electronic components.
- LUR**: Handwritten red text "LUR" appearing in one location.
- interconnects integration**: A photograph of interconnects being integrated into a circuit board.
- LUR**: Handwritten red text "LUR" appearing in one location.
- LAC**: The logo of LAC (Laboratoire de l'Accélérateur Linéaire).